74LVTN16374
3.3V, 16-Bit D-Type Edge-Triggered Flip-Flops with 3-State Outputs

GENERAL DESCRIPTION

The 74LVTN16374 is high performance product designed for V_{CC} operation at 3.3V. The device is 16-bit edge-triggered D-type flip-flops with non-inverting 3-state outputs designed specifically for driving highly capacitive or relatively low-impedance loads. It is particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers and working registers.

The device can be used as two 8-bit flip-flops or one 16-bit flip-flop. On the positive transition of the clock (nCP) input, the nQn outputs of the flip-flop take on the logic levels set up at the nDn inputs.

An output enable ($n\overline{OE}$) input can be used to place the 8 outputs in either a normal logic state (high or low logic levels) or a high-impedance state.

$n\overline{OE}$ does not affect internal operations of the flip-flop. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

FEATURES

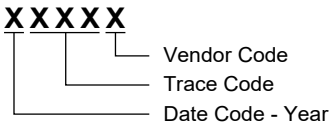
- **16-Bit Edge-Triggered Flip-Flop**
- **3-State Buffers**
- **Output Capability: +64mA/-32mA**
- **TTL Input and Output Switching Levels**
- **Input and Output Interface Capability to Systems at 5V Supply**
- **Live Insertion and Extraction Permitted**
- **Power-Up Reset**
- **Power-Up 3-State**
- **No Bus Current Loading When Output is Tied to 5V Bus**
- **-40℃ to +125℃ Operating Temperature Range**
- **Available in a Green TSSOP-48 Package**

PACKAGE/ORDERING INFORMATION

MODEL	PACKAGE DESCRIPTION	SPECIFIED TEMPERATURE RANGE	ORDERING NUMBER	PACKAGE MARKING	PACKING OPTION
74LVTN16374	TSSOP-48	-40℃ to +125℃	74LVTN16374XTS48G/TR	74LVTN16374 XTS48 XXXXX	Tape and Reel, 2500

MARKING INFORMATION

NOTE: XXXXX = Date Code, Trace Code and Vendor Code.



Green (RoHS & HSF): SG Micro Corp defines "Green" to mean Pb-Free (RoHS compatible) and free of halogen substances. If you have additional comments or questions, please contact your SGMICRO representative directly.

ABSOLUTE MAXIMUM RATINGS (1)

Supply Voltage, V_{CC} ..... -0.5V to 4.6V
Input Voltage, V_I (2) ..... -0.5V to 7V
Output Voltage, V_O (2)
Output in 3-State or High-State ..... -0.5V to 7V
Input Clamping Current, I_{IK} (V_I < 0V) ..... -50mA
Output Clamping Current, I_{OK} (V_O < 0V) ..... -50mA
Output Current, I_O
Output in High-State ..... -64mA
Output in Low-State 128mA
Supply Current, I_{CC} 128mA
Ground Current, I_{GND} ..... -256mA
Junction Temperature (3) ..... +150℃
Storage Temperature Range ..... -65℃ to +150℃
Lead Temperature (Soldering, 10s) ..... +260℃
ESD Susceptibility
HBM 8000V
CDM 1000V

RECOMMENDED OPERATING CONDITIONS

Supply Voltage, V_{CC} ..... 2.7V to 3.6V
Input Voltage, V_I ..... 0V to 5.5V
High-Level Output Current, I_{OH} ..... -32mA
Low-Level Output Current, I_{OL} 64mA
Input Transition Rise and Fall Rate, Δt/ΔV
..... 10ns/V (MAX)
Operating Temperature Range ..... -40℃ to +125℃

OVERSTRESS CAUTION

1. Stresses beyond those listed in Absolute Maximum Ratings may cause permanent damage to the device. Exposure to absolute maximum rating conditions for extended periods may affect reliability. Functional operation of the device at any conditions beyond those indicated in the Recommended Operating Conditions section is not implied.

2. The input and output negative voltage ratings may be exceeded if the input and output clamp current ratings are observed.

3. The performance capability of a high-performance integrated circuit in conjunction with its thermal environment can create junction temperatures which are detrimental to reliability.

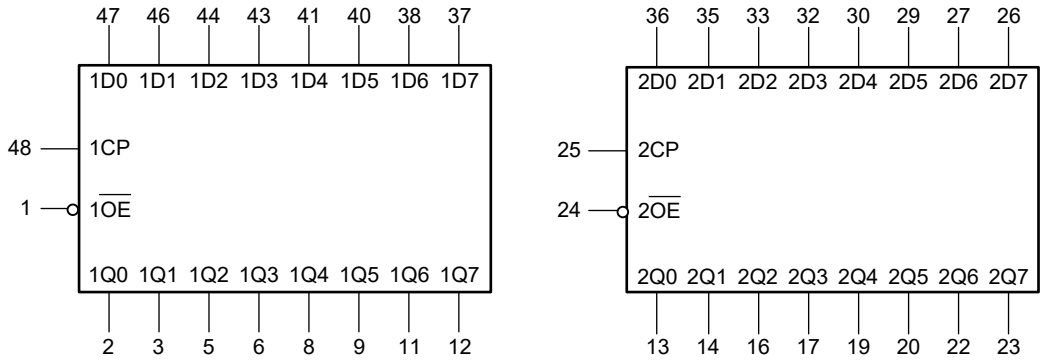
ESD SENSITIVITY CAUTION

This integrated circuit can be damaged if ESD protections are not considered carefully. SGMICRO recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage. ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because even small parametric changes could cause the device not to meet the published specifications.

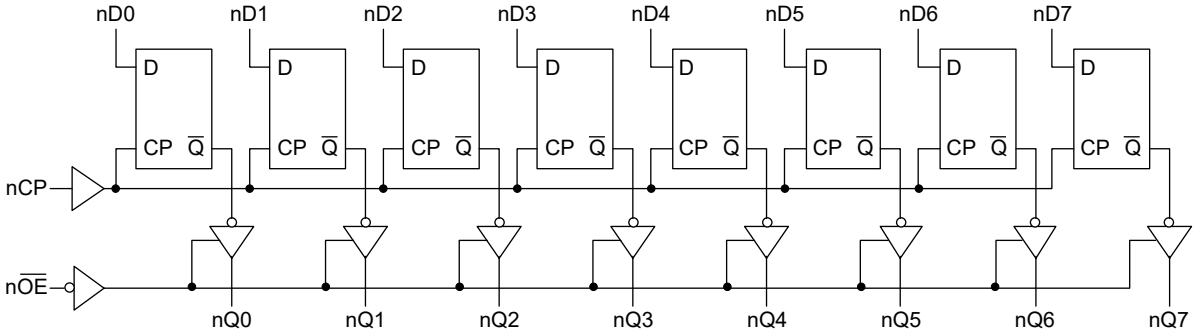
DISCLAIMER

SG Micro Corp reserves the right to make any change in circuit design, or specifications without prior notice.

LOGIC SYMBOL



LOGIC DIAGRAM



FUNCTION TABLE

OPERATING MODE	CONTROL INPUT			INTERNAL REGISTER	OUTPUT
	$n\overline{OE}$	nCP	nDn		nQn
Load and Read Register	L	↑	l	L	L
	L	↑	h	H	H
Hold	L	NC	*X*	NC	NC
Disable Outputs	H	NC	*X*	NC	Z
	H	↑	nDn	nDn	Z

H = High Voltage Level

L = Low Voltage Level

↑ = Low-to-High Clock Transition

h = High Voltage Level One Set-Up Time Prior to the Low-to-High Clock Transition

l = Low Voltage Level One Set-Up Time Prior to Low-to-High Clock Transition

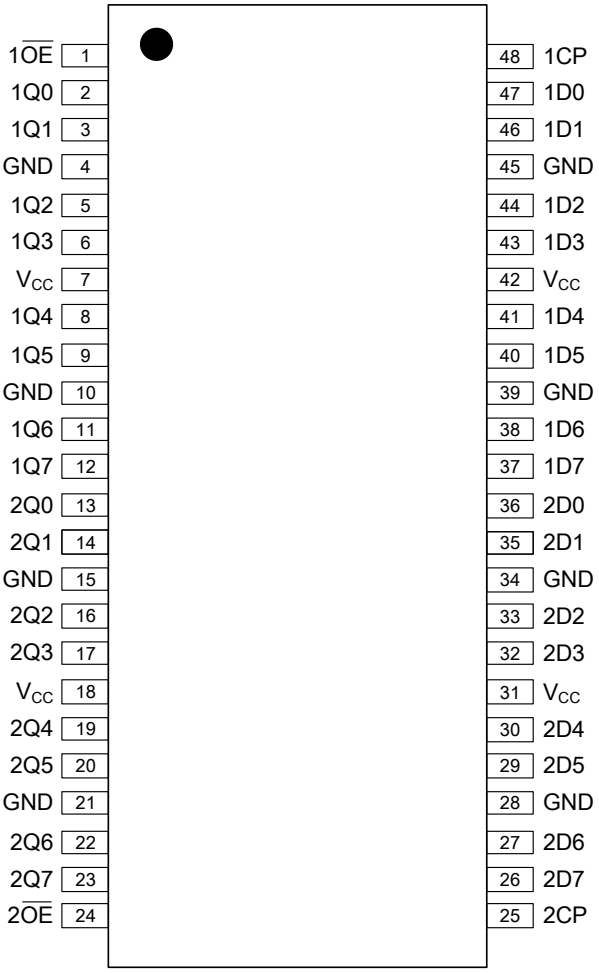
Z = High-Impedance State

NC = No Change

X = Don't Care

PIN CONFIGURATION

(TOP VIEW)



TSSOP-48

PIN DESCRIPTION

PIN	NAME	FUNCTION
47, 46, 44, 43, 41, 40, 38, 37	1D0, 1D1, 1D2, 1D3, 1D4, 1D5, 1D6, 1D7	Data Inputs.
36, 35, 33, 32, 30, 29, 27, 26	2D0, 2D1, 2D2, 2D3, 2D4, 2D5, 2D6, 2D7	Data Inputs.
1, 24	1$\overline{OE}$, 2$\overline{OE}$	Output Enable Inputs (Active Low).
48, 25	1CP, 2CP	Clock Inputs.
2, 3, 5, 6, 8, 9, 11, 12	1Q0, 1Q1, 1Q2, 1Q3, 1Q4, 1Q5, 1Q6, 1Q7	Data Outputs.
13, 14, 16, 17, 19, 20, 22, 23	2Q0, 2Q1, 2Q2, 2Q3, 2Q4, 2Q5, 2Q6, 2Q7	Data Outputs.
4, 10, 15, 21, 28, 34, 39, 45	GND	Ground.
7, 18, 31, 42	V_{CC}	Supply Voltage.

ELECTRICAL CHARACTERISTICS

(Full = -40℃ to +125℃, all typical values are measured at V_{CC} = 3.3V and T_A = +25℃, unless otherwise noted.)

PARAMETER	SYMBOL	CONDITIONS		TEMP	MIN	TYP	MAX	UNITS
Input Clamping Voltage	V_{IK}	V_{CC} = 2.7V, I_{IK} = -18mA		Full	-1.2	-0.78		V
High-Level Input Voltage	V_{IH}	V_{CC} = 2.7V to 3.6V		Full	2			V
Low-Level Input Voltage	V_{IL}	V_{CC} = 2.7V to 3.6V		Full			0.8	V
High-Level Output Voltage	V_{OH}	I_{OH} = -100μA, V_{CC} = 2.7V to 3.6V		Full	V_{CC} - 0.05	V_{CC} - 0.001		V
		I_{OH} = -8mA, V_{CC} = 2.7V		Full	2.45	2.6		
		I_{OH} = -32mA, V_{CC} = 3.0V		Full	2.1	2.65		
Low-Level Output Voltage	V_{OL}	V_{CC} = 2.7V	I_{OL} = 100μA	Full		0.001	0.05	V
			I_{OL} = 24mA	Full		0.15	0.28	
		V_{CC} = 3.0V	I_{OL} = 16mA	Full		0.1	0.18	
			I_{OL} = 32mA	Full		0.2	0.36	
			I_{OL} = 64mA	Full		0.4	0.55	
Power-Up Low-Level Output Voltage [1]	V_{OL_PU}	V_{CC} = 3.6V, I_{OL} = 1mA, V_I = V_{CC} or GND		Full		5	50	mV
Input Leakage Current	I_I	Control pins, V_{CC} = 3.6V, V_I = V_{CC} or GND		Full		±0.01	±1	μA
		Control pins, V_{CC} = 0V or 3.6V, V_I = 5.5V		Full		0.01	5	
		Input data pins [2], V_{CC} = 0V or 3.6V, V_I = 5.5V		Full		0.01	5	
		Input data pins [2], V_{CC} = 3.6V, V_I = V_{CC}		Full		0.01	1	
		Input data pins [2], V_{CC} = 3.6V, V_I = GND		Full	-2	-0.01		
Off-State Output Current	I_{OZ}	V_{CC} = 3.6V	V_O = 3.0V	Full		0.01	2	μA
			V_O = 0.5V	Full	-2	-0.01		
Output Leakage Current	I_{LO}	Output in high-state when V_O > V_{CC}, V_O = 5.5V, V_{CC} = 3.0V		Full		1	30	μA
Power-Up/Down Output Current	$I_{O\_PU/PD}$	V_{CC} ≤ 1.2V, V_O = 0.5V to V_{CC}, V_I = GND or V_{CC}, $n\overline{OE}$ = don't care		+25℃		0.01	10	μA
Power-Off Leakage Current	I_{OFF}	V_{CC} = 0V, V_I or V_O = 0V to 5.5V		Full		0.01	10	μA
Supply Current	I_{CC}	V_{CC} = 3.6V, V_I = GND or V_{CC}, I_O = 0A	Outputs high	Full		12	80	μA
			Outputs low	Full		12	80	
			Outputs disabled [3]	Full		12	80	
Additional Supply Current [4]	ΔI_{CC}	Per input pin, V_{CC} = 3.0V to 3.6V, one input at V_{CC} - 0.6V, other inputs at V_{CC} or GND		Full		0.2	80	μA
Input Capacitance	C_I	Input pins, V_I = 0V or 3.0V		+25℃		6		pF
Output Capacitance	C_O	Output pins nQn, outputs disabled, V_O = 0V or V_{CC}		+25℃		9		pF

NOTES:

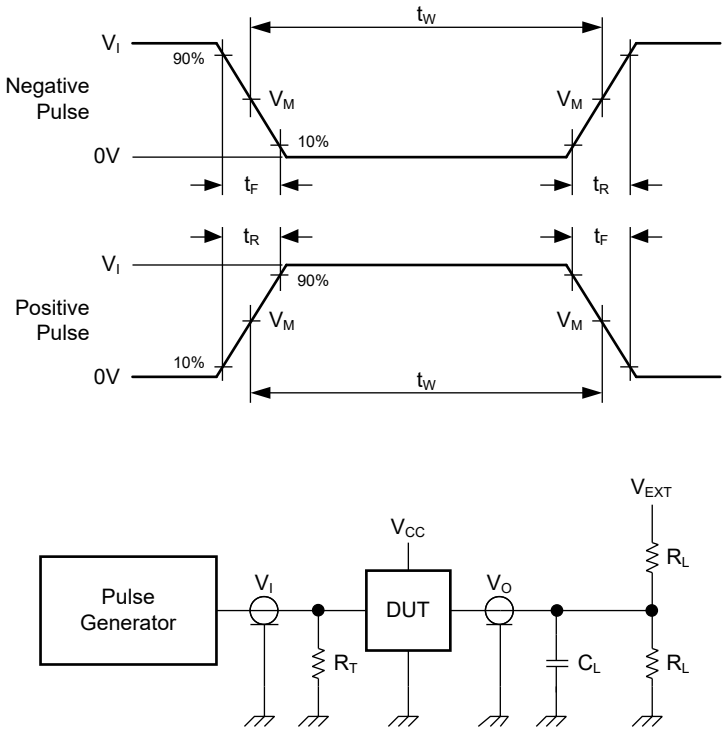
1. For valid test results, data must not be loaded into the flips-flops (or latches) after applying power.
2. Unused pins at V_{CC} or GND.
3. I_{CC} is measured with outputs pulled to V_{CC} or GND.
4. This is the increase in supply current for each input at the specified voltage level other than V_{CC} or GND.

DYNAMIC CHARACTERISTICS

(For test circuit, see Figure 1. All typical values are measured at V_{CC} = 3.3V and T_A = +25°C, unless otherwise noted.)

PARAMETER	SYMBOL	CONDITIONS		TEMP	MIN	TYP	MAX	UNITS
Maximum Frequency	f_{MAX}	nCP, V_{CC} = 3.3V ± 0.3V, see Figure 2		+25°C		150		MHz
Low to High Propagation Delay	t_{PLH}	nCP to nQn, see Figure 2	V_{CC} = 3.3V ± 0.3V	+25°C		3.4		ns
			V_{CC} = 2.7V	+25°C		3.9		
High to Low Propagation Delay	t_{PHL}	nCP to nQn, see Figure 2	V_{CC} = 3.3V ± 0.3V	+25°C		3.3		ns
			V_{CC} = 2.7V	+25°C		3.5		
Off-State to High Propagation Delay	t_{PZH}	n$\overline{OE}$ to nQn, see Figure 3	V_{CC} = 3.3V ± 0.3V	+25°C		4.3		ns
			V_{CC} = 2.7V	+25°C		3.9		
Off-State to Low Propagation Delay	t_{PZL}	n$\overline{OE}$ to nQn, see Figure 3	V_{CC} = 3.3V ± 0.3V	+25°C		4.4		ns
			V_{CC} = 2.7V	+25°C		4.3		
High to Off-State Propagation Delay	t_{PHZ}	n$\overline{OE}$ to nQn, see Figure 3	V_{CC} = 3.3V ± 0.3V	+25°C		4.5		ns
			V_{CC} = 2.7V	+25°C		4		
Low to Off-State Propagation Delay	t_{PLZ}	n$\overline{OE}$ to nQn, see Figure 3	V_{CC} = 3.3V ± 0.3V	+25°C		3.8		ns
			V_{CC} = 2.7V	+25°C		3.4		
Set-Up Time	t_{SU}	nDn to nCP, high or low, see Figure 4	V_{CC} = 3.3V ± 0.3V	+25°C		0.3		ns
			V_{CC} = 2.7V	+25°C		0.3		
Hold Time	t_H	nDn to nCP, high or low, see Figure 4	V_{CC} = 3.3V ± 0.3V	+25°C		0.2		ns
			V_{CC} = 2.7V	+25°C		0.2		
Pulse Width	t_W	nCP high, see Figure 2	V_{CC} = 3.3V ± 0.3V	+25°C		1.5		ns
			V_{CC} = 2.7V	+25°C		1.5		
		nCP low, see Figure 2	V_{CC} = 3.3V ± 0.3V	+25°C		1.5		
			V_{CC} = 2.7V	+25°C		1.5		

TEST CIRCUIT



Test conditions are given in Table 1.

Definitions for test circuit:

R_L = Load resistance.

C_L = Load capacitance including jig and probe capacitance.

R_T = Termination resistance should be equal to output impedance Z_O of the pulse generator.

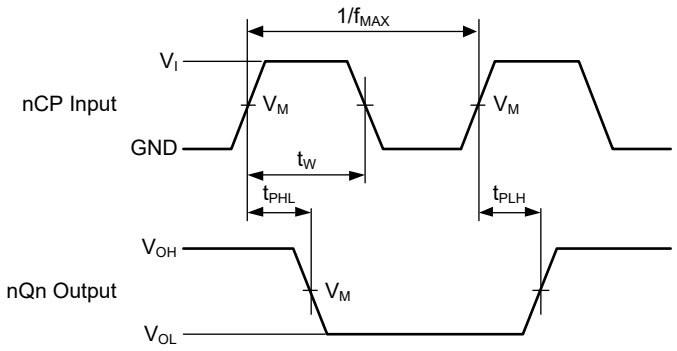
V_{EXT} = External voltage for measuring switching times.

Figure 1. Test Circuit for Measuring Switching Times

Table 1. Test Conditions

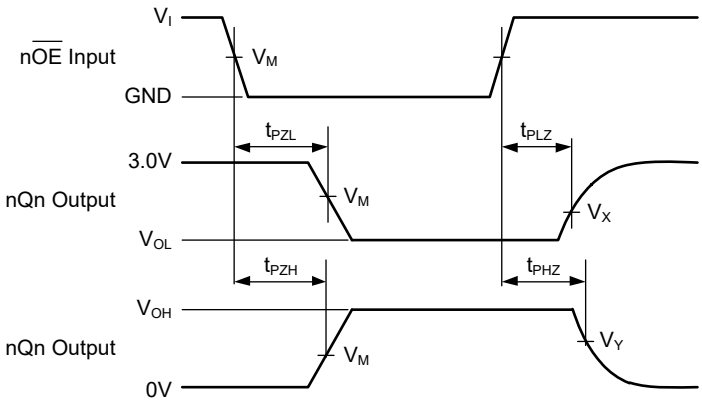
SUPPLY VOLTAGE	INPUT				LOAD		V_{EXT}		
V_{CC}	V_I	f_i	t_W	t_R, t_F	C_L	R_L	t_{PHZ}, t_{PZH}	t_{PLZ}, t_{PZL}	t_{PLH}, t_{PHL}
2.7V to 3.6V	2.7V	≤ 10MHz	500ns	≤ 2.5ns	50pF	500Ω	GND	6V	Open

WAVEFORMS



Test conditions are given in Table 1.
Measurement points are given in Table 2.
Logic levels: V_{OL} and V_{OH} are typical output voltage levels that occur with the output load.

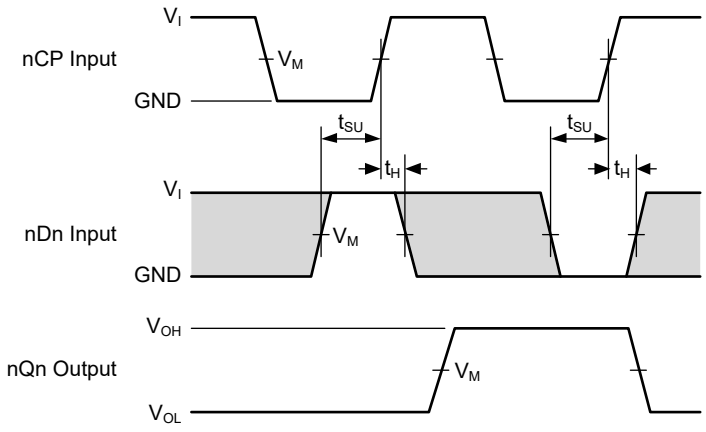
Figure 2. Clock Input to Output Propagation Delays, Clock Pulse Width and Maximum Clock Frequency



Test conditions are given in Table 1.
Measurement points are given in Table 2.
Logic levels: V_{OL} and V_{OH} are typical output voltage levels that occur with the output load.

Figure 3. Enable and Disable Times

WAVEFORMS (continued)



Test conditions are given in Table 1.
Measurement points are given in Table 2.
Logic levels: V_{OL} and V_{OH} are typical output voltage levels that occur with the output load.
The shaded areas indicate when the input is permitted to change for predictable output performance.

Figure 4. Data Set-Up and Hold Times

Table 2. Measurement Points

SUPPLY VOLTAGE	INPUT		OUTPUT		
V_{CC}	V_I	V_M	V_M	V_X	V_Y
2.7V to 3.6V	2.7V	1.5V	1.5V	V_{OL} + 0.3V	V_{OH} - 0.3V

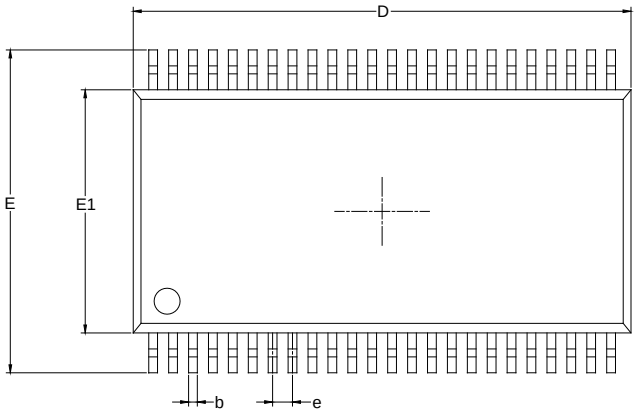
REVISION HISTORY

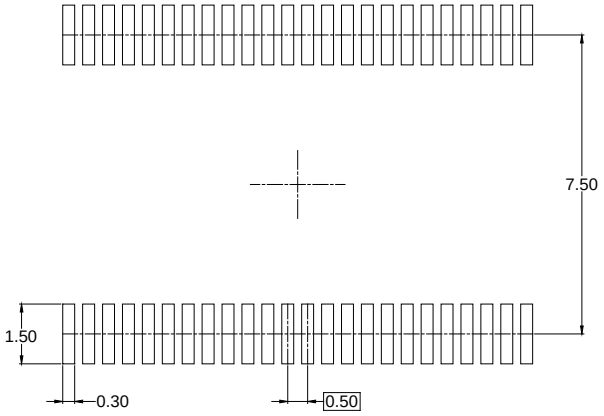
NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

Changes from Original (MARCH 2021) to REV.A	Page
Changed from product preview to production data	All

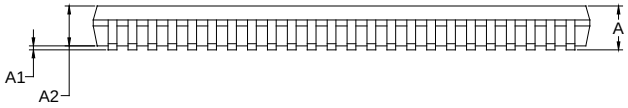
PACKAGE OUTLINE DIMENSIONS

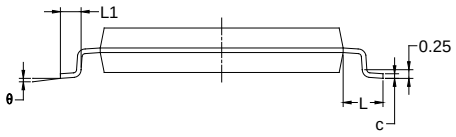
TSSOP-48





RECOMMENDED LAND PATTERN (Unit: mm)

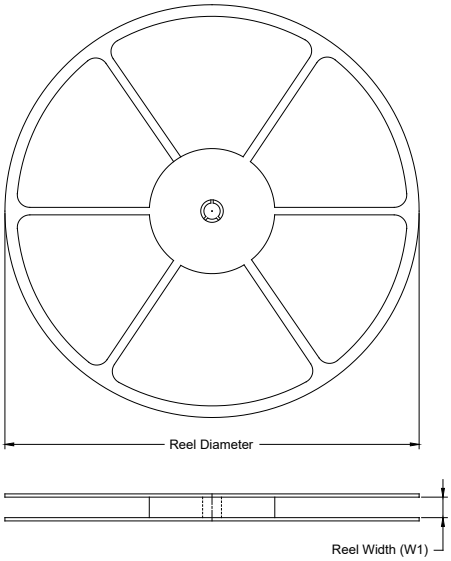




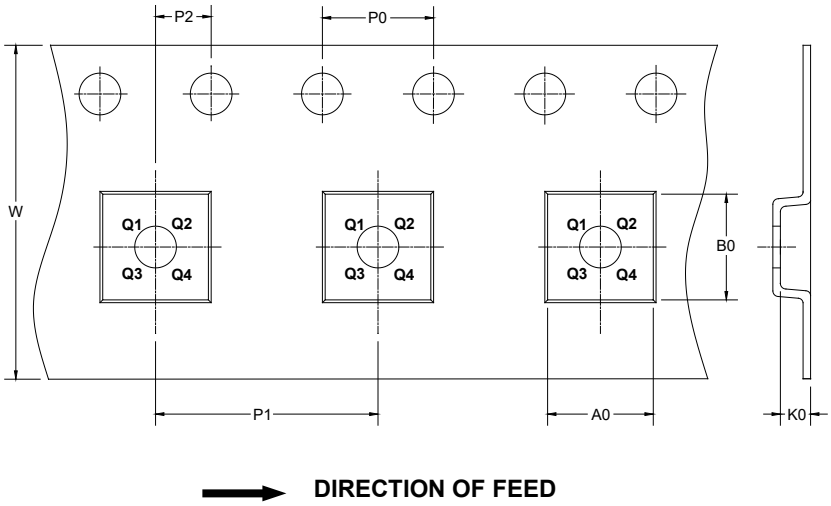
Symbol	Dimensions In Millimeters		
	MIN	MOD	MAX
A			1.20
A1	0.05	0.10	0.15
A2	0.85	0.95	1.05
b	0.18		0.26
c	0.15		0.19
D	12.40	12.50	12.60
E	7.90	8.10	8.30
E1	6.00	6.10	6.20
e	0.50 BSC		
L	1.00 REF		
L1	0.45		0.75
θ	0°		8°

TAPE AND REEL INFORMATION

REEL DIMENSIONS



TAPE DIMENSIONS



DIRECTION OF FEED

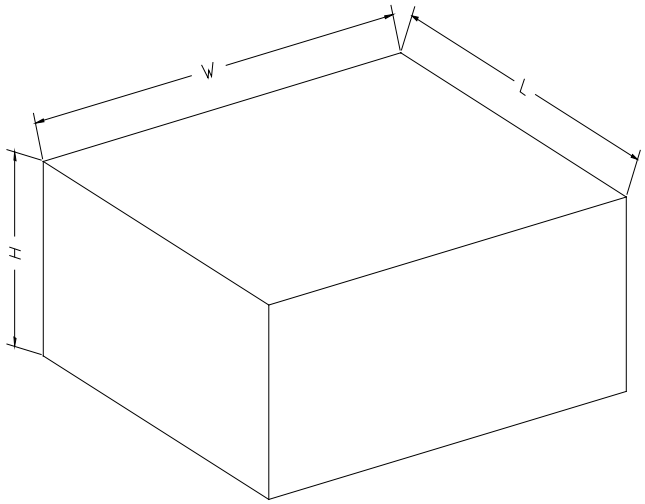
NOTE: The picture is only for reference. Please make the object as the standard.

KEY PARAMETER LIST OF TAPE AND REEL

Package Type	Reel Diameter	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P0 (mm)	P1 (mm)	P2 (mm)	W (mm)	Pin1 Quadrant
TSSOP-48	13”	24.4	8.60	13.00	1.80	4.0	12.0	2.0	24.0	Q1

DD0001

CARTON BOX DIMENSIONS



NOTE: The picture is only for reference. Please make the object as the standard.

KEY PARAMETER LIST OF CARTON BOX

Reel Type	Length (mm)	Width (mm)	Height (mm)	Pizza/Carton
13″	386	280	370	5

DD0002